



Product Change Notification / RMES-28IMGT211

Date:

11-Oct-2021

Product Category:

Smart Energy SOC

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4729 Final Notice: Implementation of Die Overcoat material with Polyimide for ATSENSEx01, ATSAM4CMxxx and ATSAM4CMx32 device families available in 20L SOIC, 32L TQFP and 100L LQFP packages.

Affected CPNs:

[RMES-28IMGT211_Affected_CPN_10112021.pdf](#)

[RMES-28IMGT211_Affected_CPN_10112021.csv](#)

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Implementation of Die Overcoat material with Polyimide layer for ATSENSEx01, ATSAM4CMxxx and ATSAM4CMx32 device families available in 20L SOIC, 32L TQFP and 100L LQFP packages.

Pre and Post Change Summary:

	Pre Change	Post Change

Fabrication Site	Microchip Fabrication site, Fab 5, Colorado Springs, USA (MCSO)	Microchip Fabrication site, Fab 5, Colorado Springs, USA (MCSO)
Die Overcoat Material	Without Polyimide layer	With Polyimide layer

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve manufacturability by implementing of Die Overcoat material (Polyimide layer). Die overcoat protect the die against scratches, package stress and increase mold compound adhesion during assembly process.

Change Implementation Status: In Progress

Estimated First Ship Date: October 28,2021 (date code: 2144)

Time Table Summary:

	October 2021				
Workweek	41	42	43	44	45
Qual Report Availability		X			
Final PCN Issue Date		X			
Estimated Implementation Date				X	

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: October 11, 2021: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_RMES-28IMGT211_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

ATSENSE101A-SU
ATSENSE301A-AU
ATSENSE201HA-AU
ATSENSE301HA-AU
ATSENSE201A-AU
ATSENSE301A-AN
ATSENSE301A-ANR
ATSENSE101A-SUR
ATSENSE301A-AUR
ATSENSE201HA-AUR
ATSENSE301HA-AUR
ATSENSE201A-AUR
ATSAM4CMP8CB-AU
ATSAM4CMS8CB-AU
ATSAM4CMS16CC-AU
ATSAM4CMS4CC-AU
ATSAM4CMS8CC-AU
ATSAM4CMP16CC-AU
ATSAM4CMP8CC-AU
ATSAM4CMP8CB-AUR
ATSAM4CMS8CB-AUR
ATSAM4CMS16CC-AUR
ATSAM4CMS4CC-AUR
ATSAM4CMS8CC-AUR
ATSAM4CMP16CC-AUR
ATSAM4CMP8CC-AUR
ATSAM4CMS32CB-AU
ATSAM4CMP32CB-AU
ATSAM4CMS32CB-AUR
ATSAM4CMP32CB-AUR